



CyberOptics Demonstrates New WaferSense and ReticleSense Auto Multi Sensors (AMS)

*Leveling, Vibration and Humidity Measurement All-in-one Sensor Saves Time and Expenses
While Improving Yields*

TAIPEI, Taiwan — SEMICON Taiwan 2015 — August 27, 2015— [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, will demonstrate the first wireless sensor to combine leveling, vibration and Relative humidity (RH) measurement in an all-in-one device at [SEMICON Taiwan](#) in Taipei, September 2-4, 2015 in booth #426.

For semiconductor equipment diagnostics, qualification or preventative maintenance, the wireless, real-time, all-in-one WaferSense® and ReticleSense® Auto Multi Sensors (AMS) speed leveling, vibration and Relative Humidity (RH) measurement to help save time and expenses while increasing yields.

The WaferSense® Auto Multi Sensor (AMS) can travel through virtually any tool with its thinner and lighter form factor and can also operate at higher temperatures for greater versatility. The ReticleSense Auto Multi Sensor (AMSR) incorporates the same combination of measurement capabilities in a reticle shaped form factor to travel anywhere a reticle travels. For these individual measurements in semiconductor fab processes, legacy methods are not real-time, can be complicated or inefficient, and can be costly when tools need to be taken off-line for various processes.

“Semiconductor Fabs worldwide have relied on CyberOptics’ wireless, real-time measurement devices to improve yields and equipment uptime. Several Semiconductor OEM standards require the use of WaferSense and ReticleSense devices as the best known method (BKM) for various applications,” said Ferris Chen, Director of Sales, CyberOptics, Asia. “We’ve now combined two of our proven measurement technologies, leveling and vibration, and added a new RH measurement capability into an all-in-one Auto Multi Sensor. This combination device provides equipment and process engineers even more convenience and saves even more time.”

About the WaferSense and ReticleSense Line

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensor (APS) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm, 300mm and 450mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ), the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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